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CHIP-PACKAGING WITH BONDING OPTIONS CONNECTED TO A PACKAGE SUBSTRATE

Appl. No.

: 10/709,428

Confirmation No. 3427

Applicant

Cheng-Yen Huang

Filed

May 5, 2004

TC/A.U.

2814

Examiner

TRINH, HOA B

Docket No.

FTCP0035USA

Customer No.

27765

Commissioner for Patents

P.O. Box 1450

Alexandria VA 22313-1450

AMENDMENT AND REQUEST FOR CONTINUED EXAMINATION

5 Sir:

In response to the Office action of January 8, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 Remarks/Arguments begin on page 5 of this paper.